

HOSTAFORM® M10AE

High melt strength

POM copolymer

Stiff-flowing type with high melt strength; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation.

Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470

Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm.

Ranges of applications: For extrusion blow molding, and for injection molding thick-walled, void-free molded parts.

Rheological properties

Melt volume-flow rate	0.9 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile Modulus	2800 MPa	ISO 527-1/-2
Yield stress, 50mm/min	65 MPa	ISO 527-1/-2
Yield strain, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	25 %	ISO 527-1/-2
Shear Modulus	889 MPa	ISO 6721
Tensile creep modulus, 1h	2400 MPa	ISO 899-1
Tensile creep modulus, 1000h	1200 MPa	ISO 899-1
Charpy impact strength, 23 °C	220 ^[P] kJ/m ²	ISO 179/1eU
Charpy impact strength, -30 °C	200 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23 °C	10 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30 °C	8 kJ/m ²	ISO 179/1eA

[P]: Partial Break

Thermal properties

Melting temperature, 10 °C/min	167 °C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	97 °C	ISO 75-1/-2
Vicat softening temperature, 50 °C/h, 50N	150 °C	ISO 306
Coeff. of linear therm. expansion, parallel	130 E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	28 kV/mm	IEC 60243-1
Comparative tracking index	PLC 0 PLC	UL 746A

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Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m ³	ISO 1183

Injection

Drying Temperature	100 - 120 °C	
Drying Time, Dehumidified Dryer	3 - 4 h	
Processing Moisture Content	0.15 %	
Melt Temperature Optimum	200 °C	Internal
Screw tangential speed	0.2 - 0.21 m/s	
Max. mould temperature	80 - 120 °C	
Back pressure	4 MPa	
Injection speed	slow-medium	

Characteristics

Additives	Release agent
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Additional information

Film extrusion

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Other extrusion

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Profile extrusion

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

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Sheet extrusion

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Blow molding

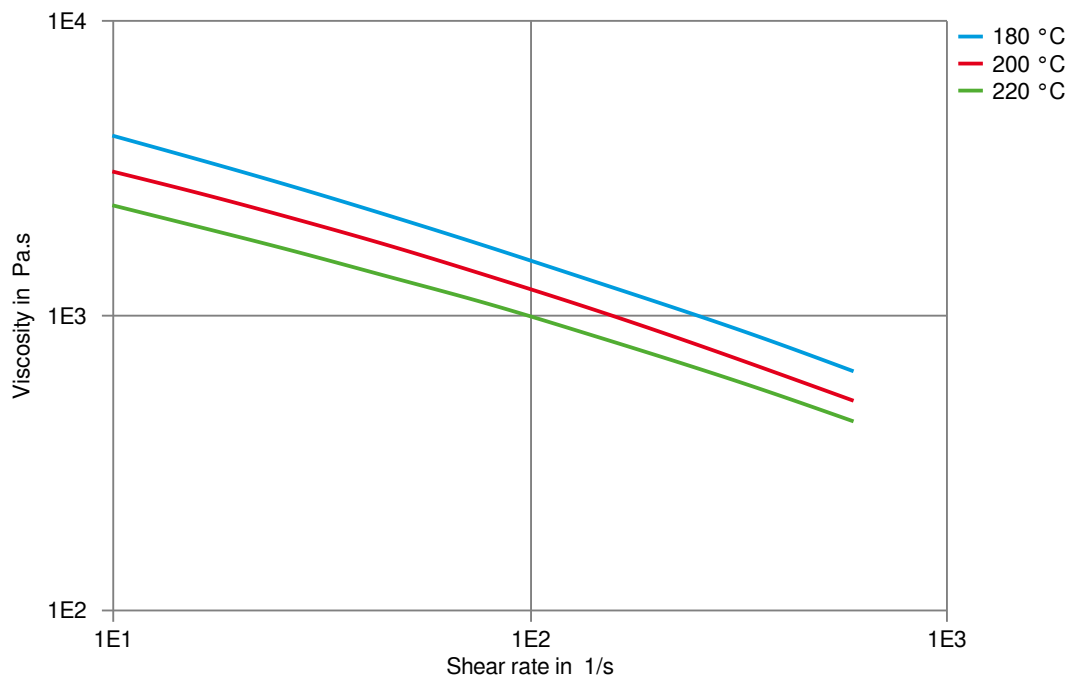
Standard extruders with plasticating screws (20 to 25 D) will fit.

Melt temperature 180-190 °C

Mould-surface temperature 60-100 °C

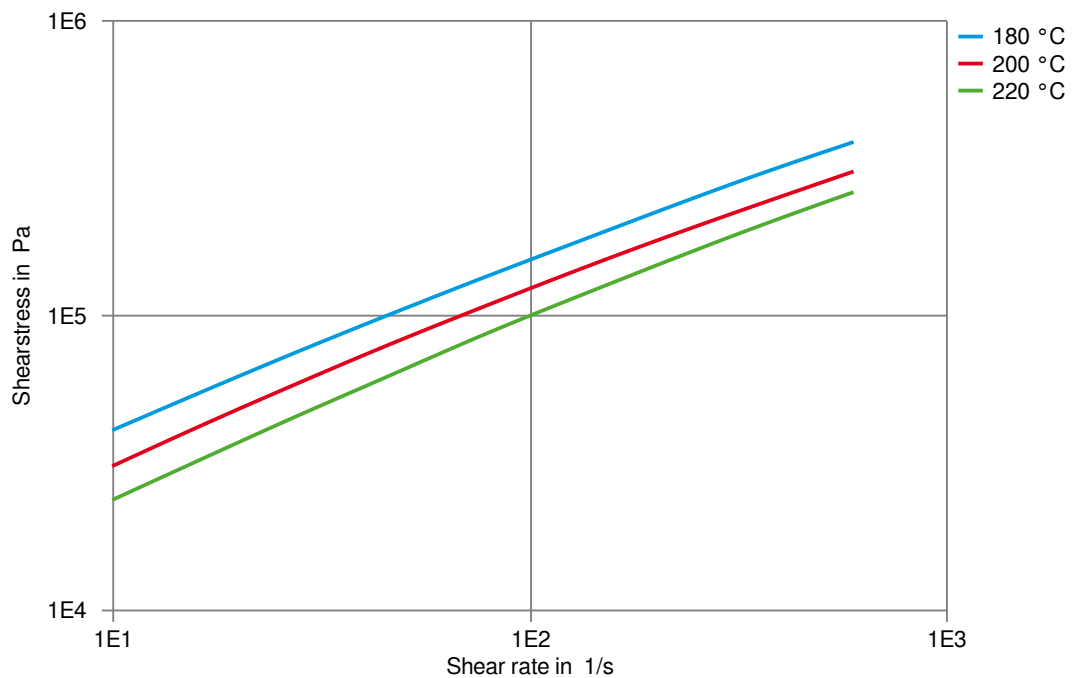
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Viscosity-shear rate



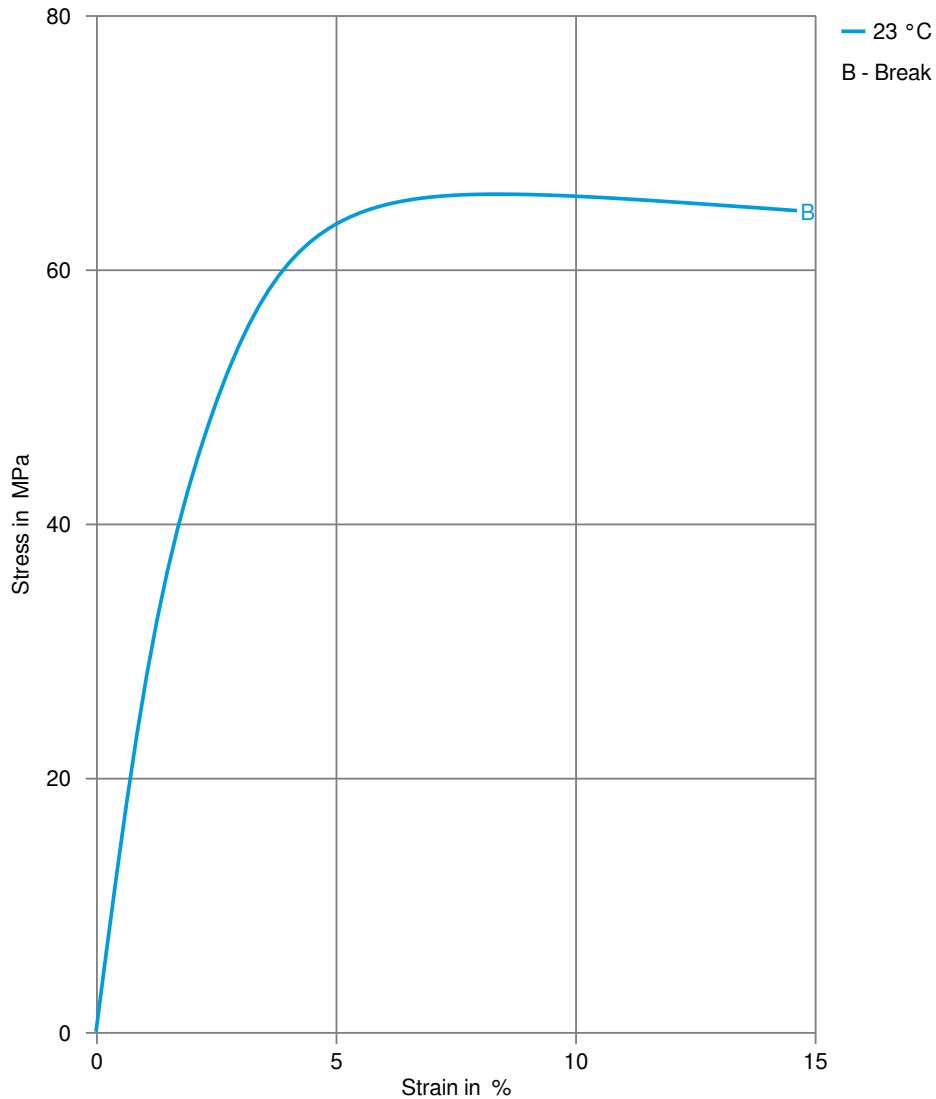
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Shearstress-shear rate



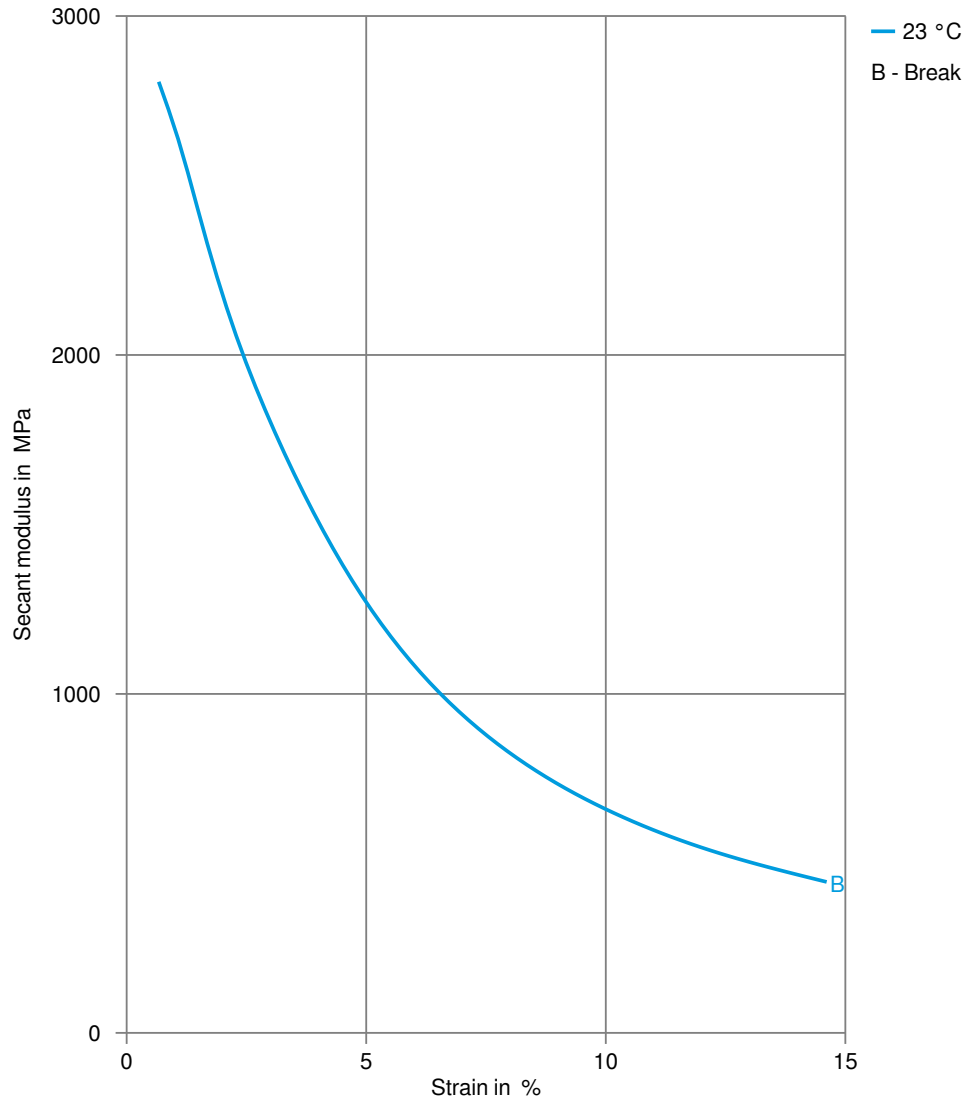
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Stress-strain



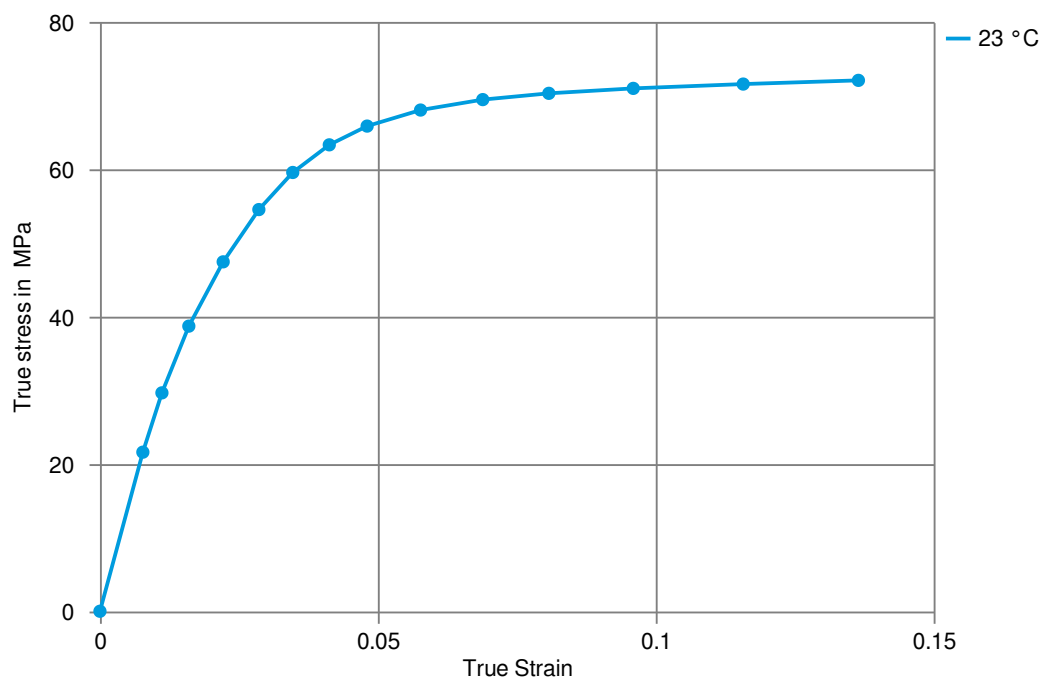
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Secant modulus-strain



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True stress-strain



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Processing Texts

Pre-drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granules

Longer pre-drying times/storage

The product can then be stored in standard conditions until processed.